

APD7002K1

N-Channel Enhancement Mosfet

AIPOWER

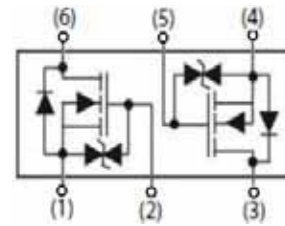
DATA SHEET

Features

- 60V,430mA
 $R_{DS(on)} < 3.0 \Omega @ V_{GS}=10V$ TYP:1.9 Ω
 $R_{DS(on)} < 4.0 \Omega @ V_{GS}=4.5V$ TYP:2.4 Ω
- Sensitive gate trigger current and
- Low Holding current.ESD protected diode.
- ESD rating:2200V HBM

Applications

- General purpose switching
- Phase control



PIN1 , 4 : S
PIN2 , 5 : G
PIN3 , 6 : D

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
72K	APD7002K1	SOT-363	-	-	3000

ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_C=25^\circ\text{C}$) ⁽³⁾	I_D	0.43	A
Continuous Drain Current ($T_C=100^\circ\text{C}$) ⁽³⁾	I_D	0.25	A
Pulsed Drain Current ^(1,3)	I_{DM}	1.7	A
Drain Power Dissipation	P_D	0.83	W
Thermal Resistance- Junction to Ambient ⁽²⁾	$R_{\theta JA}$	150	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~ +150	$^\circ\text{C}$

Notes:

1. Pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2 \%$
2. Mounted on Large Heat Sink
3. Limited by bonding wire

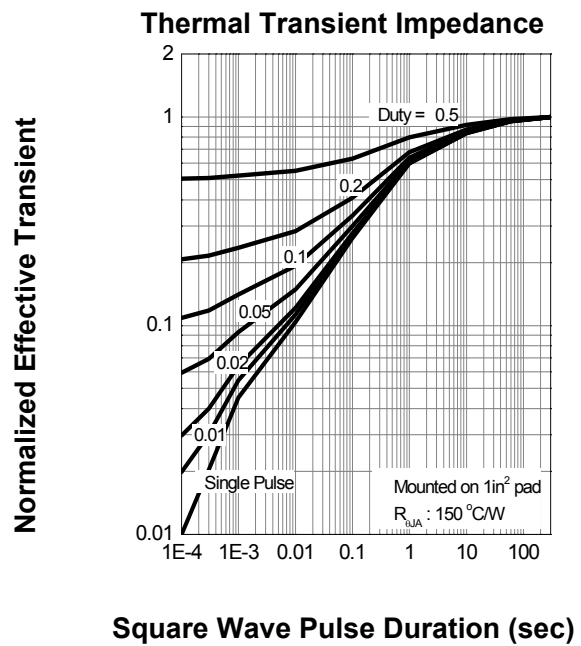
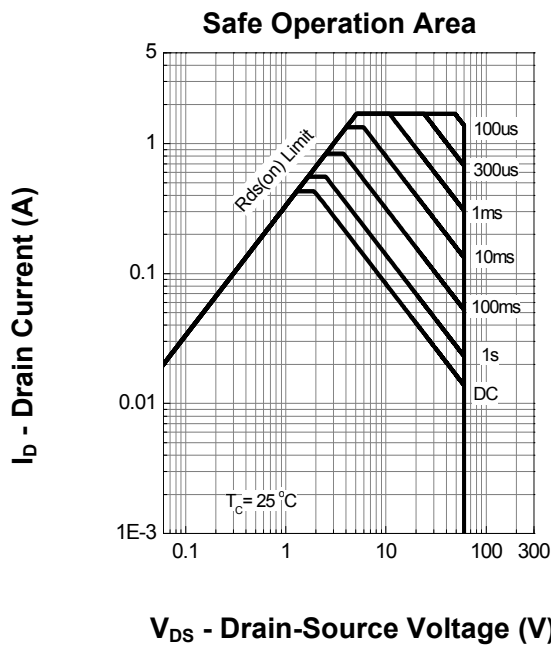
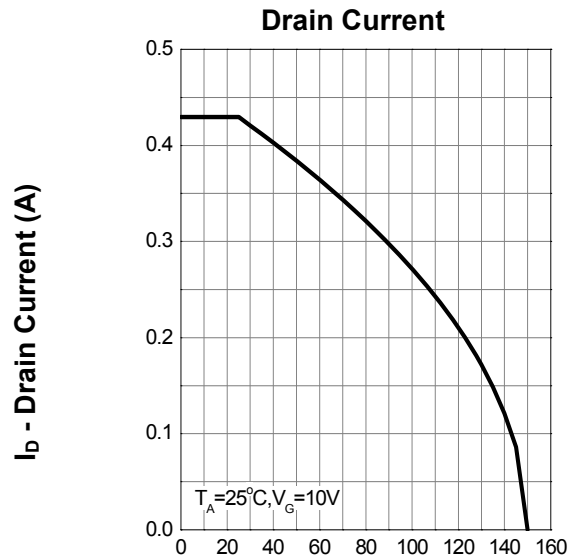
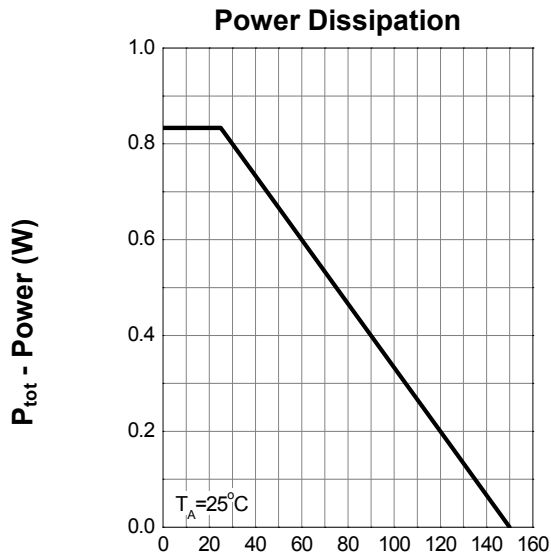
MOSFET ELECTRICAL CHARACTERISTICS(T_a=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =250μA	60	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =48V, V _{GS} = 0V	-	-	1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V	-	-	±10	μA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.0	-	2.5	V
Drain-source on-resistance	R _{DS(on)}	V _{GS} =10V, I _D =0.4A	-	1.9	3.0	Ω
		V _{GS} =4.5V, I _D =0.3A	-	2.4	4.0	Ω
Dynamic characteristics						
Input Capacitance	C _{iSS}	V _{DS} =25V, V _{GS} =0V, f =1.0MHz	-	30	-	pF
Output Capacitance	C _{oSS}		-	4.2	-	
Reverse Transfer Capacitance	C _{rSS}		-	3	-	
Switching characteristics						
Turn-on delay time	t _{d(on)}	V _{DD} =30V, I _D =0.2A, R _G =25Ω, V _G =10V	-	3.9	-	ns
Turn-on rise time	t _r		-	3.5	-	
Turn-off delay time	t _{d(off)}		-	16	-	
Turn-off fall time	t _f		-	10	-	
Total Gate Charge	Q _g	V _{DS} =10V, I _D =0.4A, V _{GS} =4.5V	-	305	-	nC
Gate-Source Charge	Q _{gs}		-	85	-	
Gate-Drain Charge	Q _{gd}		-	205	-	
Source-Drain Diode characteristics						
Diode Forward voltage	V _{SD}	T _C =25°C, V _{GS} =0V, I _S =0.4A	-	0.7	1.3	V
Diode Forward current	I _S	T _C =25°C	-	-	100	A
Body Diode Reverse Recovery Time	t _{rr}	T _C =25°C, I _F =0.4A, di/dt=100A/us		40		ns
Body Diode Reverse Recovery Charge	Q _{rr}	T _C =25°C, I _F =0.4A, di/dt=100A/us		40		uc

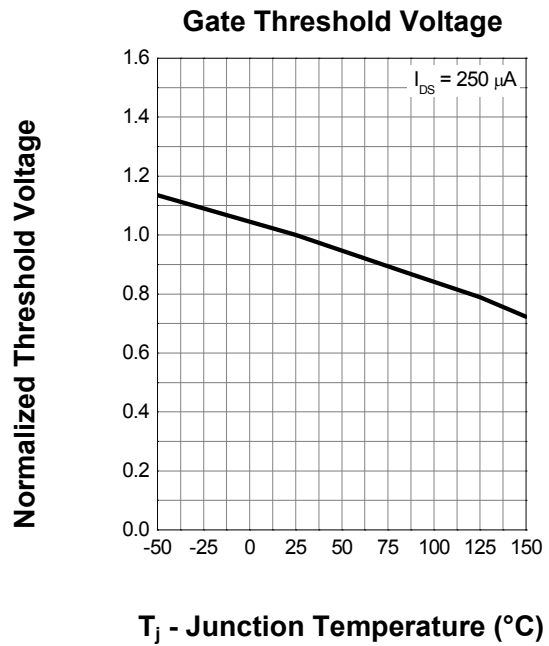
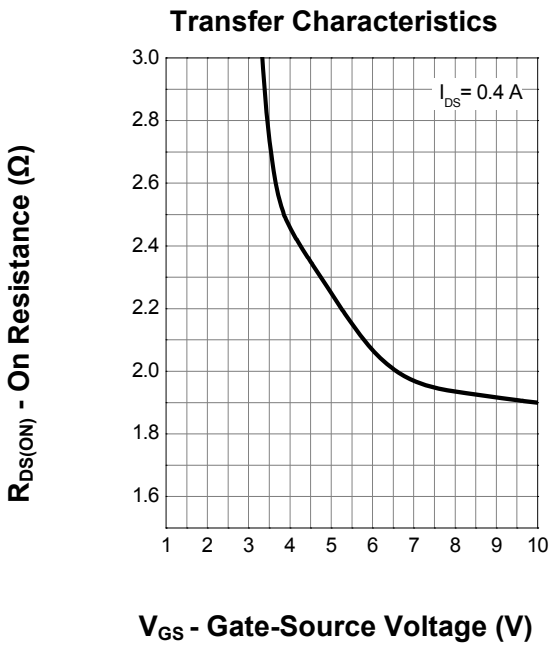
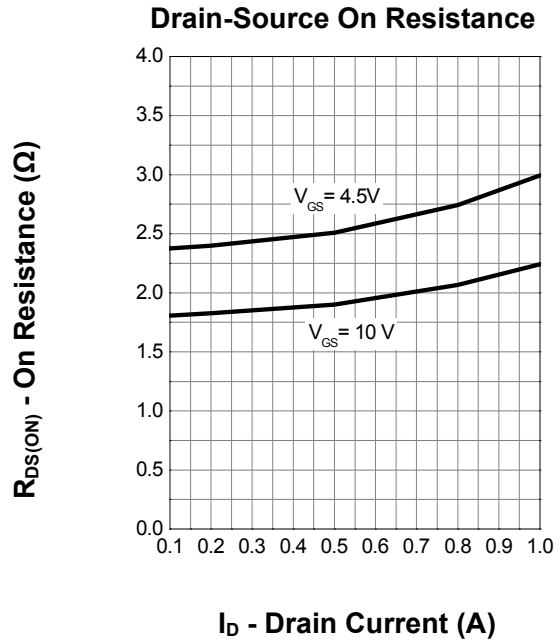
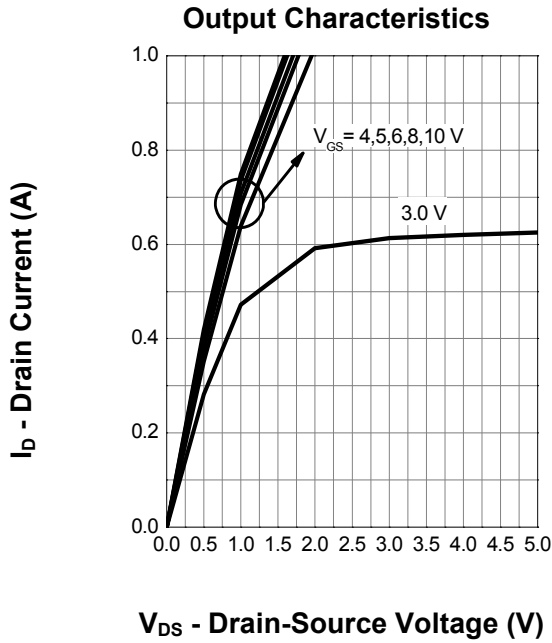
Notes:

- Pulse test ; pulse width ≤ 300 μs, duty cycle ≤ 2%
- Guaranteed by design, not subject to production testing

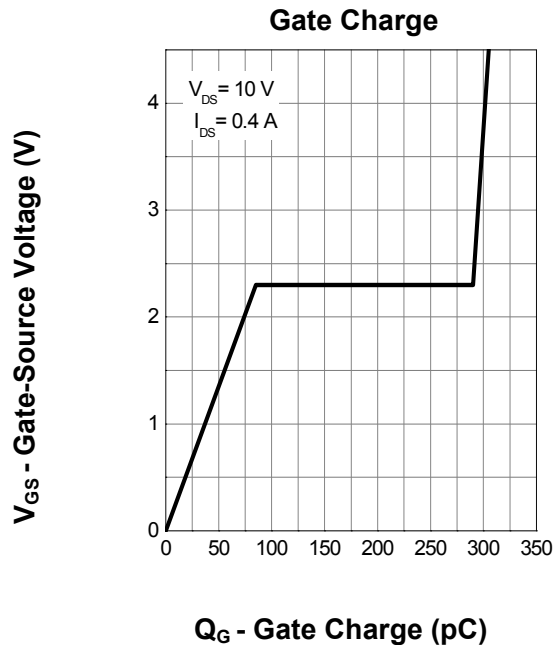
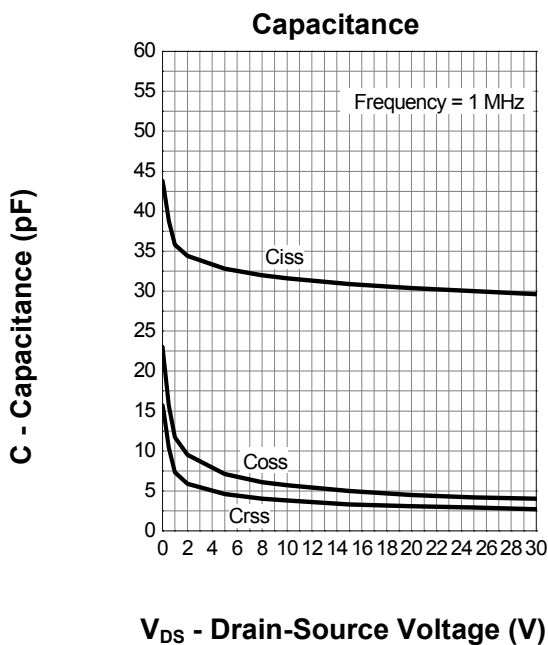
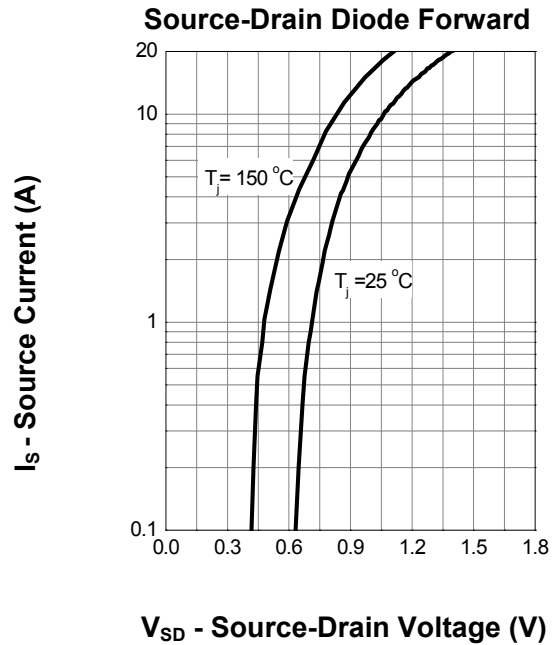
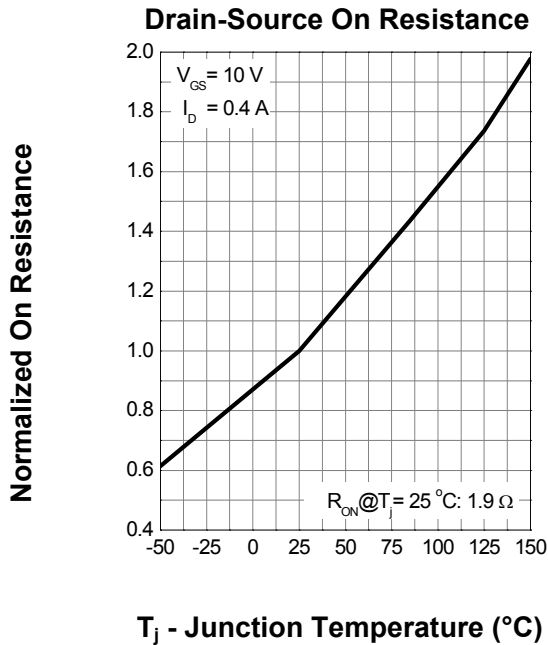
Typcal Characteristics (cont.)



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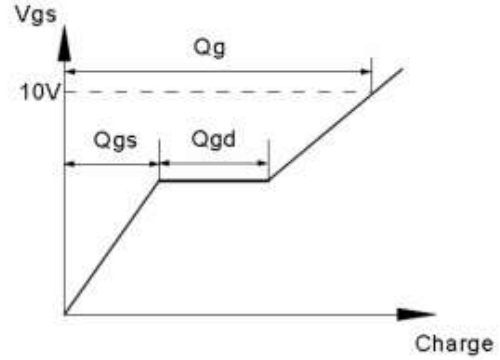
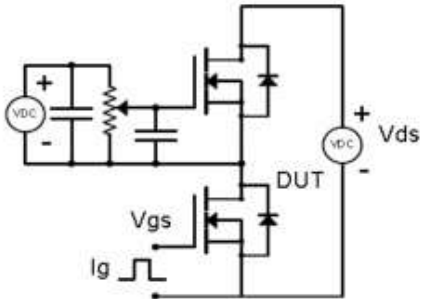


Typcal Characteristics (cont.)

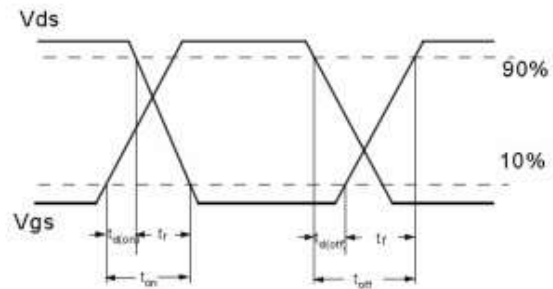
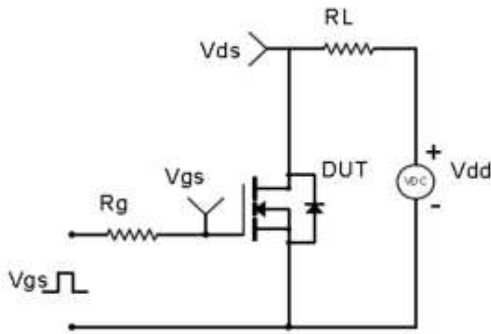


Test Circuit & Waveform

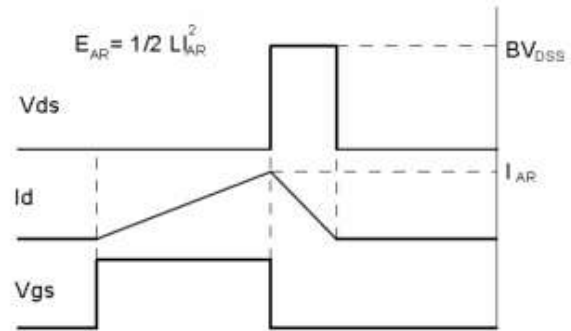
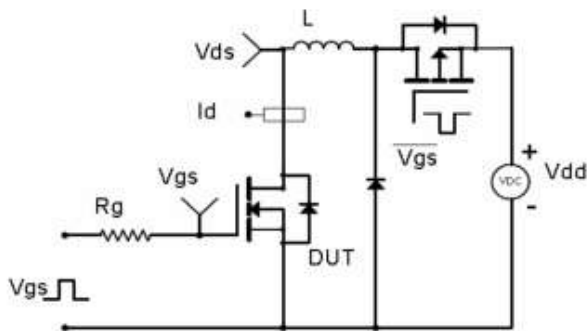
Gate Charge Test Circuit & Waveform



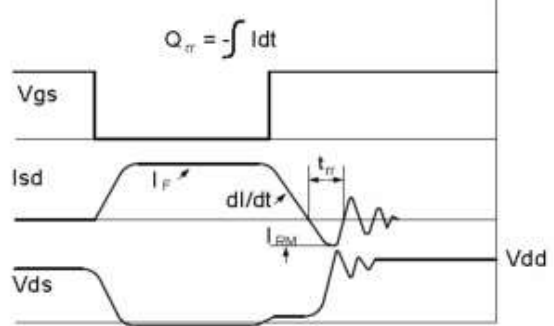
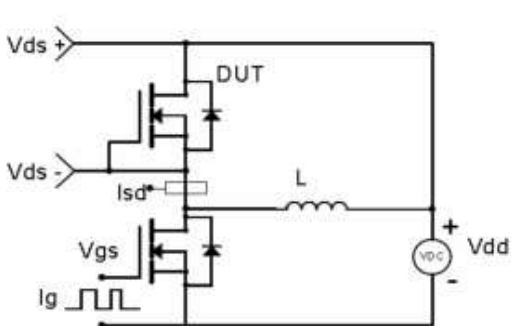
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Dimensio

